



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

Revisio

Datum:

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PRINTED CIRCUIT BOARDS

01

4.11.2001

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 097 FR4 35 L20.35 P06

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_097_FR4_35_L20.35_p06

Layers	in μ	Material	Build-Up	Assembly			
Layer-1	35 μ	Copper		A1			
	60 μ	Prepreg			(60 μ PrePreg-Type: 1080)		
	60 μ	Prepreg					
Layer-2	35 μ	Copper			B		
	200 μ	L-FR4					
Layer-3	35 μ	Copper					A2
	60 μ	Prepreg					
	60 μ	Prepreg					
Layer-4	35 μ	Copper				A2	
	200 μ	L-FR4					
	35 μ	Copper					
Layer-5	35 μ	Copper		A2			
	60 μ	Prepreg					
	60 μ	Prepreg					
Layer-99	35 μ	Copper			A2		

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